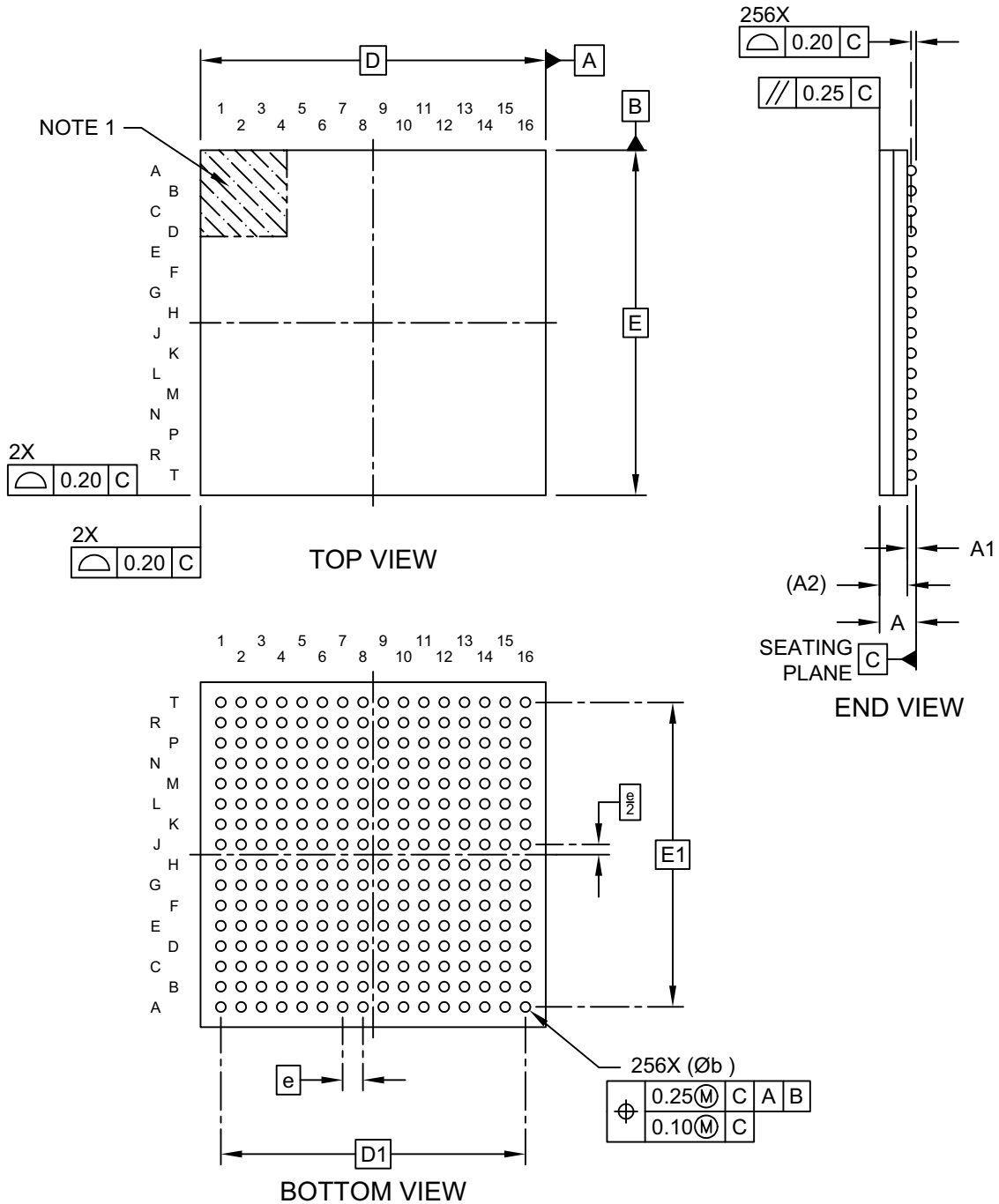


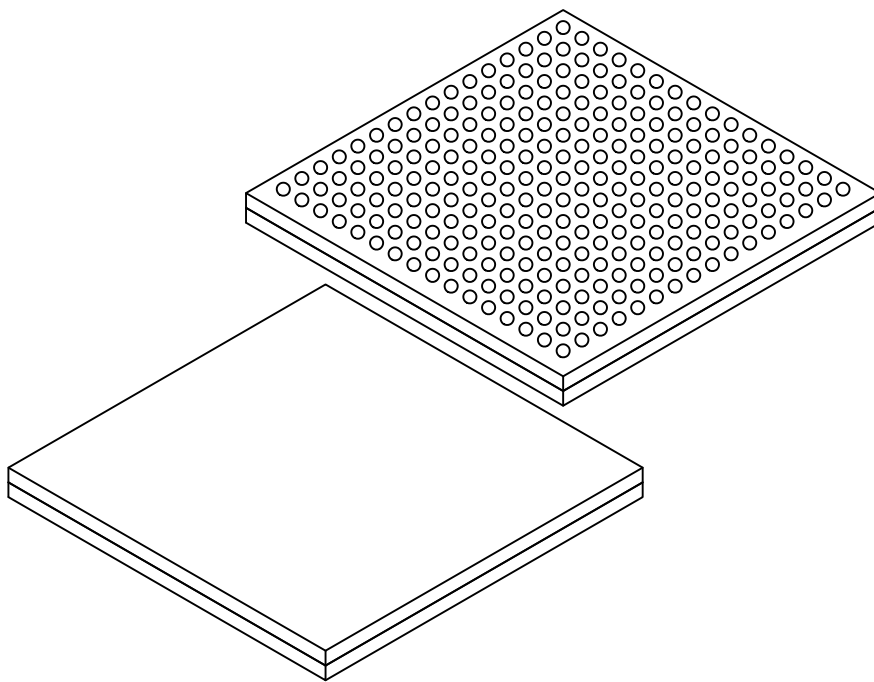
256-Ball Plastic Ball Grid Array Package (3EC) - 17x17x1.8 mm Body [PBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



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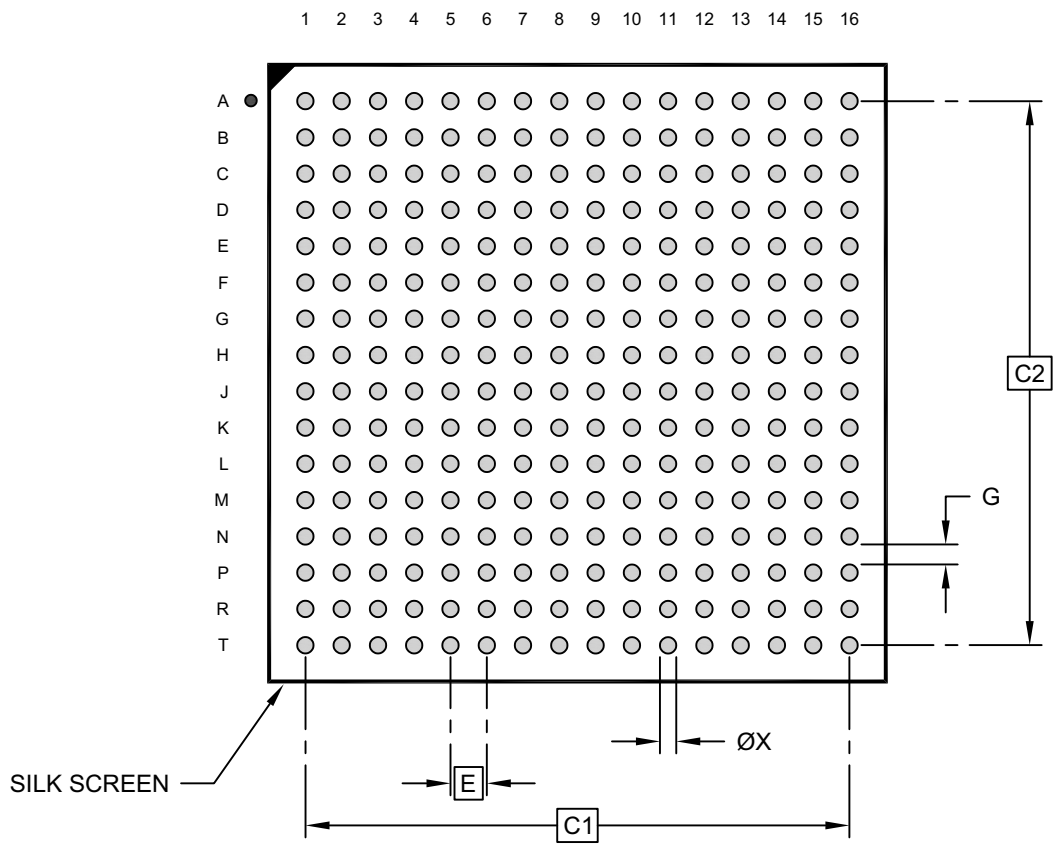
Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Terminals	N	256		
Pitch	e	1.00 BSC		
Overall Height	A	-	-	1.80
Ball Height	A1	0.31	-	0.43
Molded Package Thickness	A2	1.37 REF		
Overall Length	D	17.00 BSC		
Ball Array Length	D2	15.00 BSC		
Overall Width	E	17.00 BSC		
Ball Array Width	E2	15.00 BSC		
Ball Diameter	b	0.45	0.50	0.64

Notes:

1. Terminal A1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.

256-Ball Plastic Ball Grid Array Package (3EC) - 17x17x1.8 mm Body [PBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	1.00 BSC		
Contact Pad Spacing	C1	15.00 BSC		
Contact Pad Spacing	C2	15.00 BSC		
Contact Pad Width (X256)	X			0.45
Contact Pad to Contact Pad	G	0.55		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.